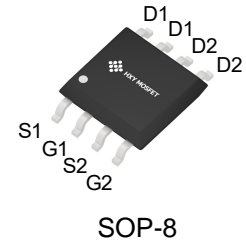




## Description

The HXY10H03S uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

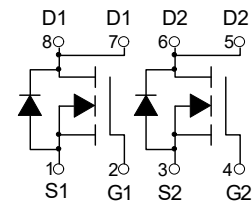


## General Features

$V_{DS} = 30V$   $I_D = 11.5A$   
 $R_{DS(ON)} < 30m\Omega$  @  $V_{GS}=10V$   
 $R_{DS(ON)} < 42m\Omega$  @  $V_{GS}=4.5V$

## Application

Battery protection  
Load switch  
Uninterruptible power supply



Dual N-Channel MOSFET

## Ordering Information

Product ID	Pack	Brand	Qty(PCS)
HXY10H03S	SOP-8	HXY MOSFET	3000

## Absolute Maximum Ratings@ $T_J=25^{\circ}C$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^{\circ}C$	Drain Current, $V_{GS}$ @ 4.5V	11.5	A
$I_D@T_A=70^{\circ}C$	Drain Current, $V_{GS}$ @ 4.5V	7.8	A
$I_{DM}$	Pulsed Drain Current	42	A
$P_D@T_A=25^{\circ}C$	Total Power Dissipation	3.2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	62.5	$^{\circ}C/W$



**Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.5	2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note3</small>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	10	13	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	-	16	22.5	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1.0MHz	-	633	-	pF
C <sub>oss</sub>	Output Capacitance		-	120	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	99	-	pF
Q <sub>g</sub> e	Total Gate Chrg	V <sub>DS</sub> =15V, I <sub>D</sub> =10A, V <sub>GS</sub> =10V	-	15	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	4.7	-	nC
Q <sub>gd</sub>	Gate-Drain(“Miller”) Charge		-	3.6	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =30V,I <sub>D</sub> =18A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =10V	-	5	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	8	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	21	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	7	-	ns
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	11.5	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	72	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =18A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =18A,dI/dt=100A/μs	-	7	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	5.9	-	nC

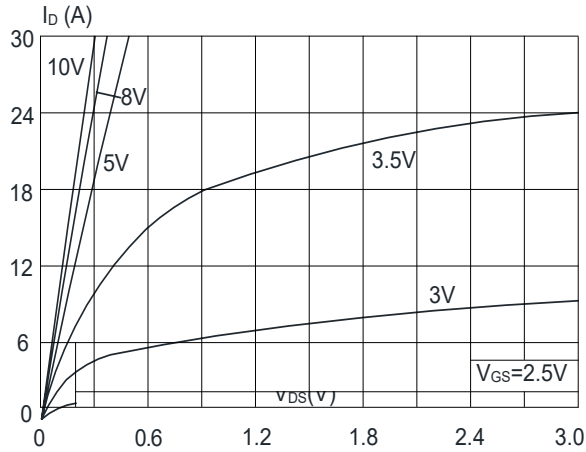
Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=20A$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

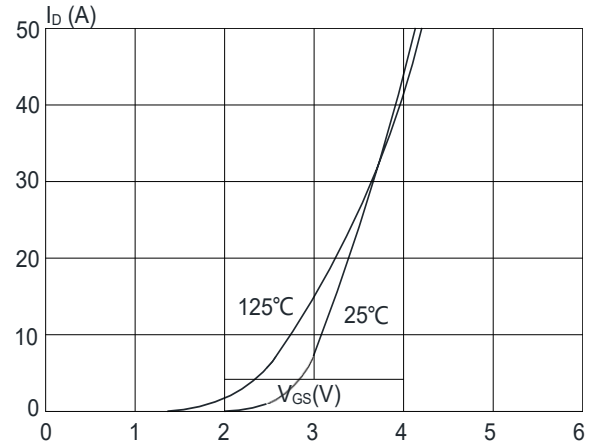


## Typical Electrical And Thermal Characteristics

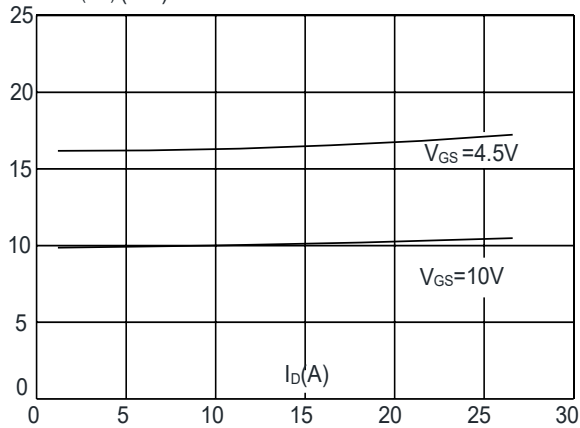
**Figure1:** Output Characteristics



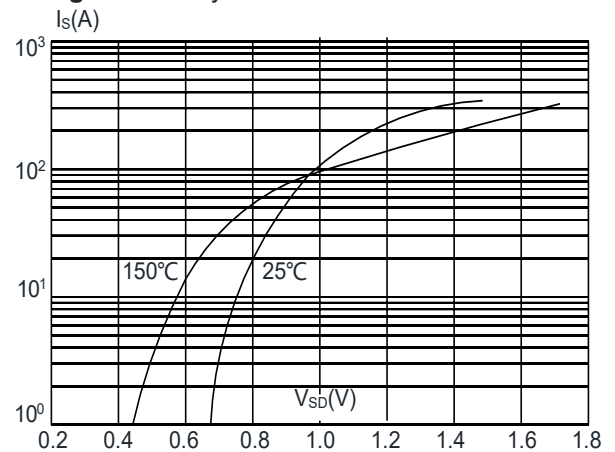
**Figure 2:** Typical Transfer Characteristics



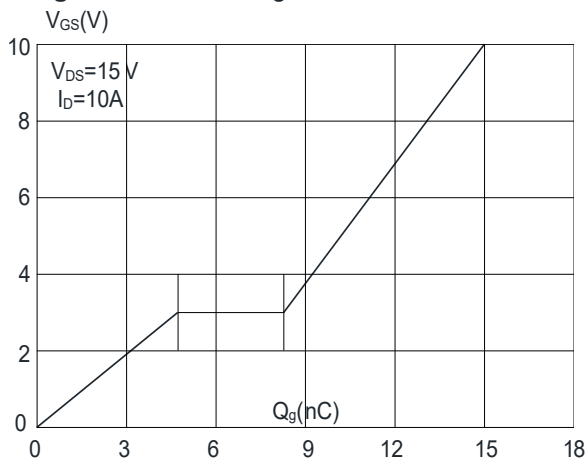
**Figure 3:** On-resistance vs. Drain Current



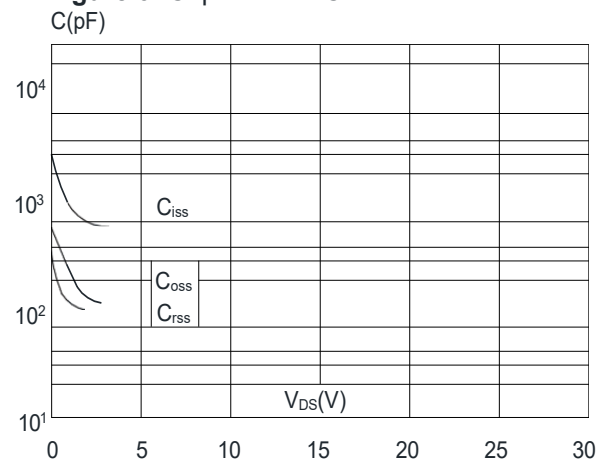
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

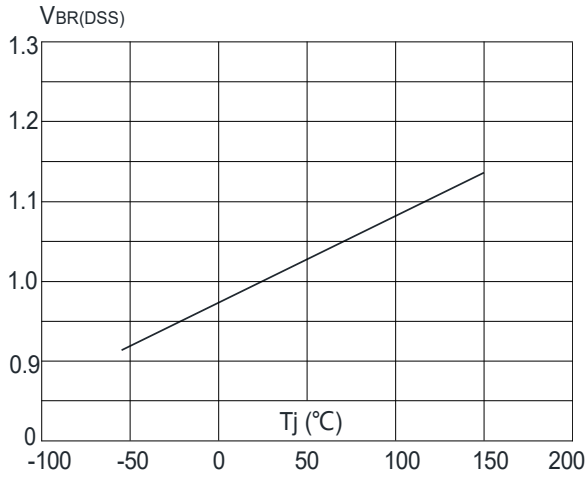


**Figure 6:** Capacitance Characteristics

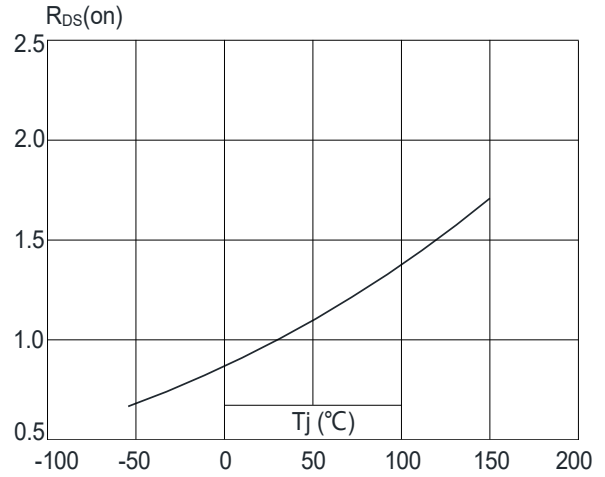




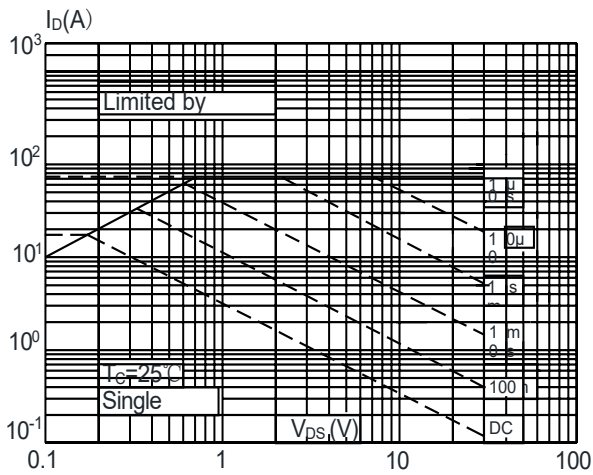
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



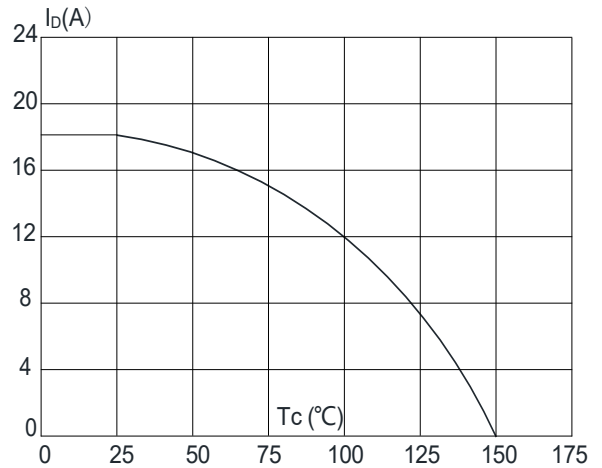
**Figure 8:** Normalized on Resistance vs. Junction Temperature



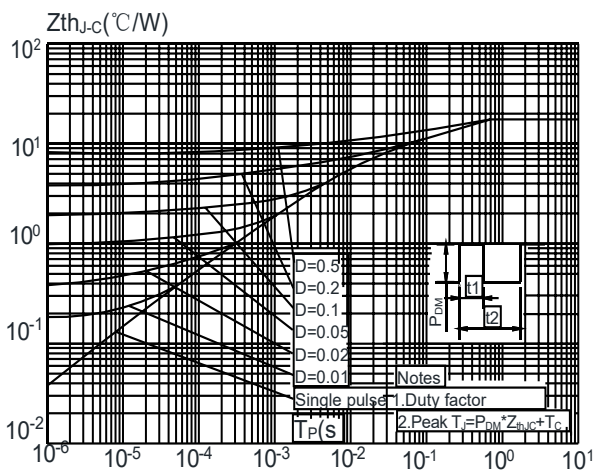
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

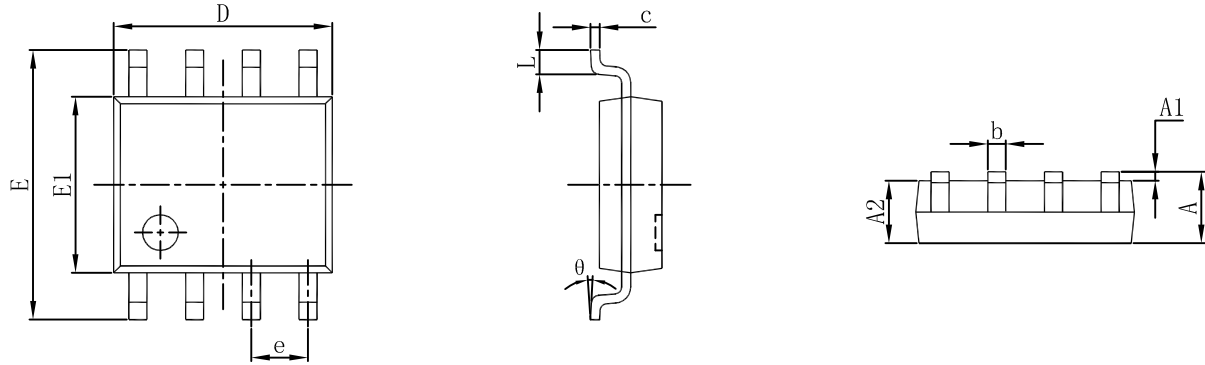


**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

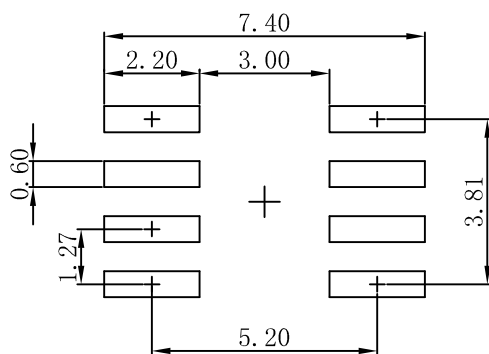




## SOP-8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Note:  
1. Controlling dimension; in millimeters.  
2. General tolerance:  $\pm 0.05\text{mm}$ .  
3. The pad layout is for reference purposes only.



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